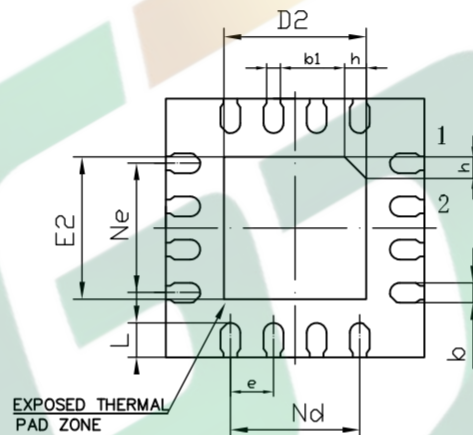
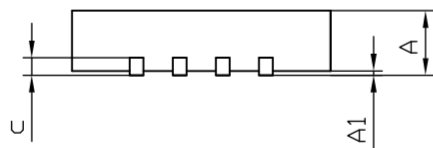


TOP VIEW



BOTTOM VIEW



SIDE VIEW

| SYMBOL | MIN | NOM | MAX |
|--------|-----------|------|------|
| A | 0.7 | 0.75 | 0.8 |
| A1 | - | 0.02 | 0.05 |
| b | 0.18 | 0.25 | 0.3 |
| b1 | 0.16REF | | |
| c | 0.18 | 0.2 | 0.25 |
| D | 2.9 | 3.0 | 3.1 |
| D2 | 1.55 | 1.65 | 1.75 |
| e | 0.5BSC | | |
| Nd/Ne | 1.50BSC | | |
| E | 2.9 | 3.0 | 3.1 |
| E2 | 1.55 | 1.65 | 1.75 |
| L | 0.35 | 0.4 | 0.45 |
| h | 0.2 | 0.25 | 0.3 |
| 载体尺寸 | 1.85*1.85 | | |

NOTES:

1. ALL DIMENSIONS REFER TO JEDEC STANDARD MO-229 (VEED-4/WEED-4)
2. DIMENSION D DOES NOT INCLUDE MOLD FLASH
3. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH
4. FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.



上海季丰电子科技有限公司

GIGA FORCE ELECTRONICS CO., Limited

| | | | | |
|----|------------|----------------|----------------------------------|--------|
| 制图 | 王磊 | Title | QFN16L (3X3X0.75) -P0.5 (CU&PPF) | |
| 核准 | 何桂港 | POD No | POD-SHJF-08 | |
| 日期 | 2022. 3. 6 | DIMENSIONS IN: | mm | Rev: A |